

L Number	Hits	Search Text	DB	Time stamp
1	17948	tether\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:07
2	1736	tether\$2 and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:10
3	1	("5472085").PN.	USPAT	2003/03/04 12:32
4	1	("6179127").PN.	USPAT	2003/03/04 12:25
5	1098	(chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:36
6	324	((chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole))) and((substrate or carrier or support or wafer) near (semiconductor or silicon or si or GA\$2 or (gallium adj arsenide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:41
7	0	((chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole))) and((substrate or carrier or support or wafer) near (semiconductor or silicon or si or GA\$2 or (gallium adj arsenide)))) and tether\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:40
8	0	((chip or die) same ((substrate or carrier or support or wafer) near (trench or aperture or hole))) and tether\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:40
9	1736	tether\$2 and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:40
10	1461	(tether\$2 and (chip or die)) and(substrate or carrier or support or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:41
11	371	(tether\$2 and (chip or die)) and ((substrate or carrier or support or wafer)with (silicon or ga\$2 or si))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:48
12	4387	206/\$.ccls. and (chip or die or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 12:52
13	114	206/\$.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:15
14	8	206/710.cccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18
15	0	206/7111.cccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:17

16	0	206/711.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18
17	0	206/711.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18
18	568	257/668.ccls. and ((chip or die) near (semiconductor or IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/04 13:18